WHAT IS CLAIMED IS:

1	 A method of designing a phase shift mask, the method 	
2	comprising:	
3	identifying edges of a first phase region of a phase shifting	
4	mask, the first phase region being located proximate a critical poly region	
5	and the identified edges not being edges of the first phase region adjacent	
6	to the critical poly region;	
7	expanding the identified edges to define a narrow line along	
8	the edges of the first phase region; and	
9	forming a phase region boundary in the narrow line along the	
10	edges of the first phase region.	
1	2. The method of claim 1, further comprising:	
2	identifying edges of a phase 180 region of a phase shifting	
3	mask, the phase 180 region being located proximate a critical poly region	
4	and the identified edges not being edges of the phase 180 region adjacent	
5	to the critical poly region;	
6	expanding the identified edges to define a narrow line along	
7	the edges of the phase 180 region; and	
8	forming chrome in the narrow line to form a chrome	
9	boundary along the edges of the phase 180 region.	

3. The method of claim 1, further comprising: assigning phase polarities to phase regions; defining edges of the assigned phase regions; establishing a boundary around the added edges; and assigning area outside of the established boundary to have phase zero.

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- 4. The method of claim 3, wherein the phase areas are assigned a 1 phase angle of either 0 or 180. 2
- 5. The method of claim 4, further comprising generating a trim 1 mask to remove undesired patterns between phase 0 and phase 180 2 regions. 3
- The method of claim 1, wherein the narrow line has a width 6. 1 of a minimum gate width dimension. 2
- The method of claim 1, further comprising defining a 7. 1 boundary around edges of a second phase region, wherein the edges are 2 not adjacent the critical poly region. 3
- The method of claim 7, wherein defining the boundary 8. includes defining a boundary around edges having phase 0. 2
 - The method of claim 1, further comprising defining break 9. locations where phase transitions are most likely to occur.
- The method of claim 9, wherein the break locations have a 10. 1 width that permits patterning and inspection. 2
- The method of claim 1, further comprising generating a trim 11. 1 mask to remove undesired patterns between first and second phase 2 regions. 3
- A method of generating phase shifting patterns to improve 12. 1 the patterning of gates and other layers needing sub-nominal dimensions, 2 the method comprising: 3
- defining critical gate areas; 4
- creating phase areas on either side of the critical gate areas; 5

6		assigning opposite phase polarities to the phase areas on	
7	either side of the critical gate areas;		
8		enhancing phase areas with assigned phase polarities;	
9		defining break regions where phase transitions are likely to	
10	occur;		
11		generating polygons to define other edges and excluding the	
12	defined break regions; and		
13		constructing a boundary region outside of phase 0 regions to	
14	form a phase shift border.		
1	13.	The method of claim 12, further comprising:	
		correcting design rule violations; and	
2	,	applying optical proximity and process corrections to phase	
3	regions to allow proper pattern generation.		
4	rogiono to o		
1	14.	The method of claim 12, further comprising generating a trim	
2	mask to remove undesired patterns between phase 0 and phase 180		
3	regions out	side of a desired pattern.	
1	15.	The method of claim 14, wherein the generating is done by	
2	oversizing	boundary and break regions.	
1	16.	The method of claim 14, wherein the chrome border has a	
2	width of a	distance between phase 0 and phase 180 regions.	
1	SUB 17.	A method of enhancing clear field phase shift masks with a	
2	chrome bo	rder around outside edges of phase 0 and phase 180 regions,	

assigning phase polarities to phase areas, the phase areas including first phase areas and second phase areas;

defining edges of the assigned phase areas;

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	establishing a first boundary around the added edges of the		
7			
8	first phase area;		
9	forming a chrome border in the first boundary around the		
10	first phase area;		
11	establishing a second boundary around the added edges of		
12	the second phase area; and		
13	forming a phase shift border in the second boundary around		
14	the second phase area.		
1	18. The method of claim 17, wherein adding edges to the		
2	assigned phase areas includes defining break regions where phase		
3	transitions occur and generating polygons including edges but excluding		
4	break regions, wherein the polygons are merged with the assigned phase		
5	areas.		
1	19. The method of claim 17, further comprising generating a trim		
2	mask to remove undesired patterns between the first and second phase		
3	areas.		
	20. The method of claim 19, wherein the trim mask does not		
1	cover all or any of the phase shift border in the second boundary around		
2			
3	the second phase area.		
1	21. The method of claim 19, wherein the generating is done by		
2 .	oversizing the boundary and break regions.		
	22. A mask configured for use in an integrated circuit		
1	manufacturing process, the mask comprising:		
2	a critical poly section defined by first edges of a phase zero		
3			
4	region and first edges of a phase 180 region; a first chrome boundary region located outside second edges		
5			
6	of the phase 180 region, the second edges of the phase 180 region being		

- different than the first edges of the phase 180 r gion, wher in the 7
- chrome boundary region includes an opaque material; and 8
- a second chrome boundary region around second edges of 9
- the phase 0 region, the second edges of the phase 0 region being 10
- different than the first edges of the phase 0 region. 11
- 23. The mask of claim 22, further comprising a region outside of 1

defined areas having a phase of zero.

The mask of claim 22, wherein the second boundary region

includes an opaque material.